

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t3570efe#pbf

(Engineering Calculation)

TSSOP Exp. Pad

(printed on: 2020-07-11 20:31:04)

TOTAL MASS (g) : 0.071494

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002264 | 1000000 | 31666.8457031 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.024424 | 975000 | 341621.5 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000601 | 24000 | 8406.25976562 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000008 | 300 | 111.896980286 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000018 | 700 | 251.768218994 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.025051 | 1000000 | 350391.375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001770 | 1000000 | 24761.8066406 | | |
| | | External Plating Total: | | | | 0.001770 | 1000000 | 24761.8066406 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000683 | 1000000 | 9553.20507812 | | |
| Internal Plating Total: | | | | 0.000683 | 1000000 | 9553.20507812 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000746 | 750000 | 10434.3925781 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000249 | 250000 | 3482.79345703 | | |
| Die Attach Total: | | | | 0.000995 | 1000000 | 13917.1875 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006015 | 150000 | 84132.5390625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.032882 | 820000 | 459924.59375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001003 | 25000 | 14029.0830078 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000201 | 5000 | 2811.41162109 | | |
| | | Encapsulation Total: | | | | 0.040101 | 1000000 | 560897.5625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000630 | 1000000 | 8811.88769531 | | |
| | | | | | TOTAL MASS (g) : | 0.071494 | | |